

## Supporting Information

### Soldering of Copper using Graphene-Phosphoric Acid Gel

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**Table S1**

Element	Series	unn. C (Wt %)	Norm. C (Wt %)	Atom. C (at %)	Error (Wt %)
Carbon	K- Series	19.06	19.06	50.56	7.03
Oxygen	K- Series	7.22	7.22	14.38	2.84
Phosphorous	K- Series	0.54	0.54	0.56	0.15
Chlorine	K- Series	0.48	0.48	0.43	0.14
Copper	L- Series	64.46	64.46	32.32	21.14
Tin	L- Series	4.24	4.24	1.14	0.52
Lead	M- Series	3.99	3.99	0.61	0.53

**Table S1:** Concentration of different elements present in the sample on the basis of Wt% and atomic (molar) ratios